TEXAS INSTRUMENTS

SN74LV1T32

SCLS741A −NOVMEBER 2013−REVISED FEBRUARY 2014

SN74LV1T32 Single Power Supply 2-Input Positive OR Gate CMOS Logic Level Shifter

1 Features

- Single-Supply Voltage Translator at 5.0/3.3/2.5/1.8V V_{CC}
- Operating Range of 1.8V to 5.5V
- Up Translation
  - 1.2V[1] to 1.8V at 1.8V V_{CC}
  - 1.5V[1] to 2.5V at 2.5V V_{CC}
  - 1.8V[1] to 3.3V at 3.3V V_{CC}
  - 3.3V to 5.0V at 5.0V V_{CC}
- Down Translation
  - 3.3V to 1.8V at 1.8V V_{CC}
  - 3.3V to 2.5V at 2.5V V_{CC}
  - 5.0V to 3.3V at 3.3V V_{CC}
- Logic Output is Referenced to V_{CC}
- Output Drive
  - 8mA Output Drive at 5V
  - 7mA Output Drive at 3.3V
  - 3mA Output Drive at 1.8V
- Characterized up to 50MHz at 3.3V V_{CC}
- 5V Tolerance on Input Pins
- –40°C to 125°C Operating Temperature Range
- Pb-Free Packages Available: SC-70 (DCK)
  - 2 × 2.1 × 0.65 mm (Height 1.1mm)
- Latch-Up Performance Exceeds 250mA Per JESD 17
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Supports Standard Logic Pinouts
- CMOS Output B Compatible with AUP1G and LVC1G Families

[1] Refer to the V_{IH}/V_{IL} and output drive for lower V_{CC} condition.

2 Applications

- Industrial controllers
- Telecom
- Portable applications
- Servers
- PC and notebooks
- Automotive

3 Description

SN74LV1T32 is a low voltage CMOS gate logic that operates at a wider voltage range for industrial, portable, telecom, and automotive applications. The output level is referenced to the supply voltage and is able to support 1.8V/2.5V/3.3V/5V CMOS levels.

The input is designed with a lower threshold circuit to match 1.8V input logic at V_{CC} = 3.3V and can be used in 1.8V to 3.3V level up translation. In addition, the 5V tolerant input pins enable down translation (e.g. 3.3V to 2.5V output at V_{CC} = 2.5V). The wide V_{CC} range of 1.8V to 5.5V allows generation of desired output levels to connect to controllers or processors.

The SN74LV1T32 is designed with current-drive capability of 8 mA to reduce line reflections, overshoot, and undershoot caused by high-drive outputs.

Device Information

ORDER NUMBER	PACKAGE	BODY SIZE
SN74LV1T32DBVR	SOT-23 (5)	2,90mm x 1,60mm
SN74LV1T32DCKR	SC70 (5)	2,00mm x 1,25mm

DCK/DBV/DRL PACKAGE
(TOP VIEW)

Table of Contents

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (December 2013) to Revision A	**Page**
• Updated document formatting.	1
• Updated Electrical Characteristics table.	6
• Updated V_{CC} values for V_{IH} parameter in the ELECTRICAL CHARACTERISTICS table.	6
• Removed I_{OH} = −2.3 mA test condition for V_{OH} parameter.	6
• Removed I_{OH} = −2.3 mA test condition for V_{OL} parameter.	7

Function Table

INPUT (Lower Level Input)		OUTPUT (V_{CC} CMOS)
A	B	Y
H	X	H
X	H	H
L	L	L

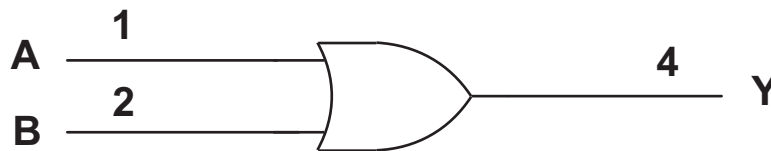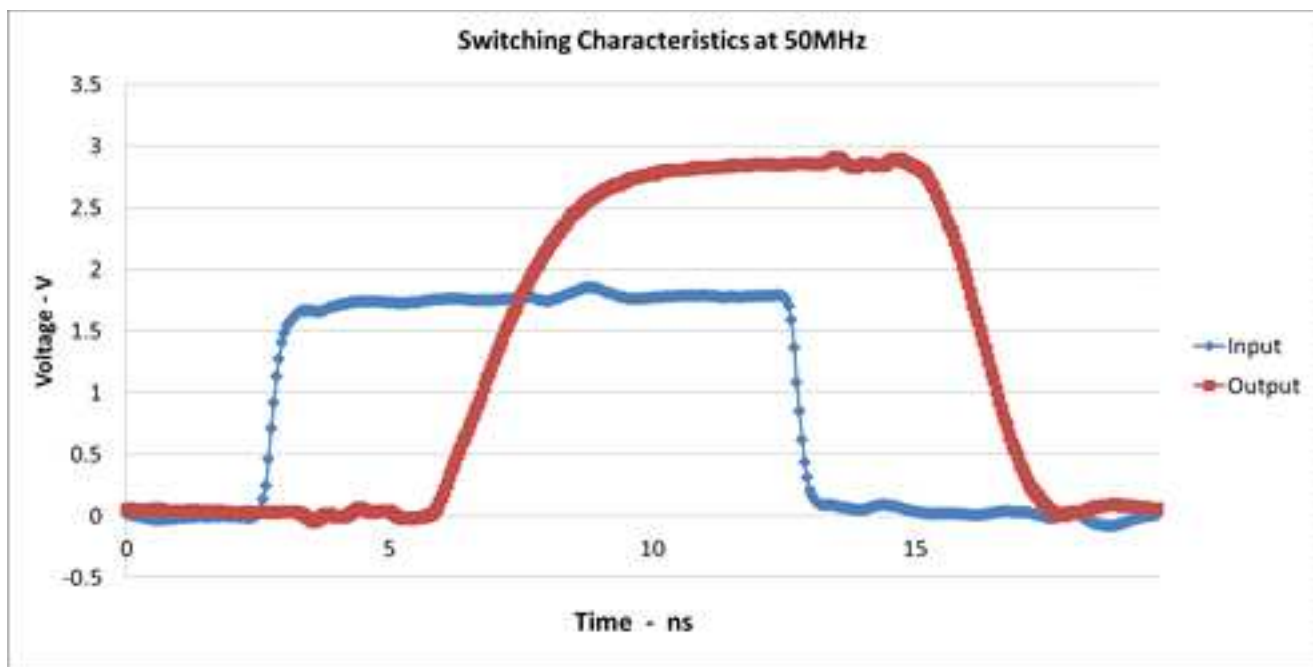| SUPPLY V_{CC} = 3.3V		
A	B	Y
V_{IH}(min) =1.35 V V_{IL}(max) =0.08 V		V_{OH}(min) = 2.9 V V_{OL}(max)= 0.2 V

Figure 1. Logic Diagram

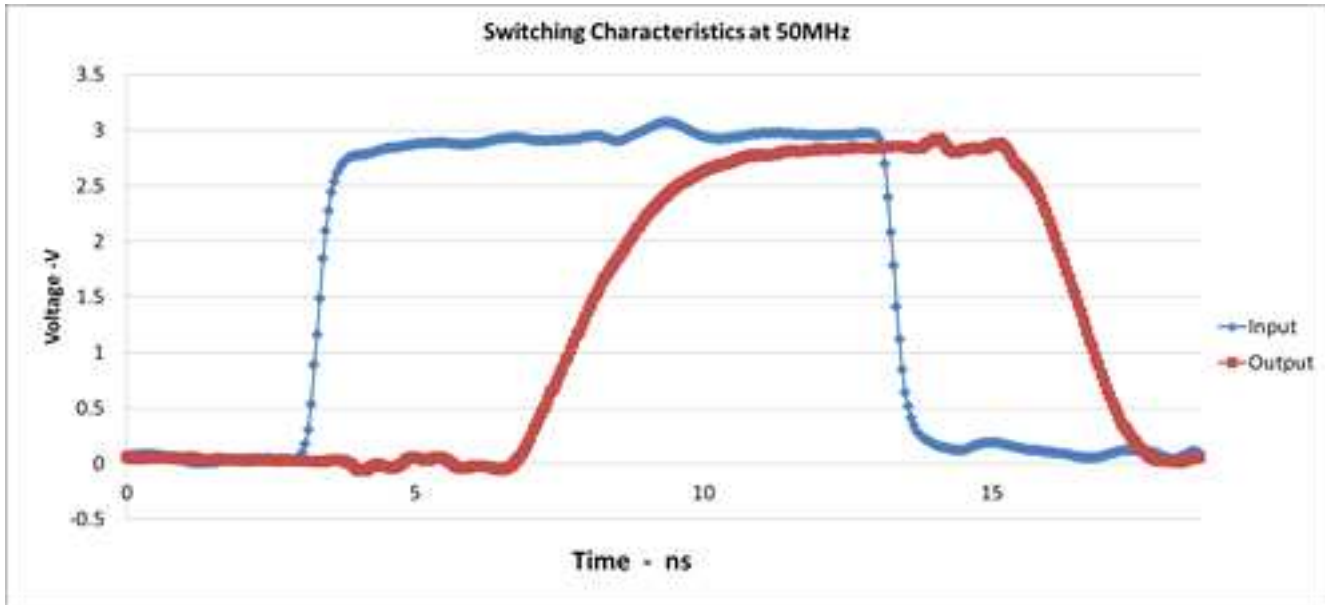**Figure 2. Excellent Signal Integrity (1.8V to 3.3V at 3.3V V_{CC})**

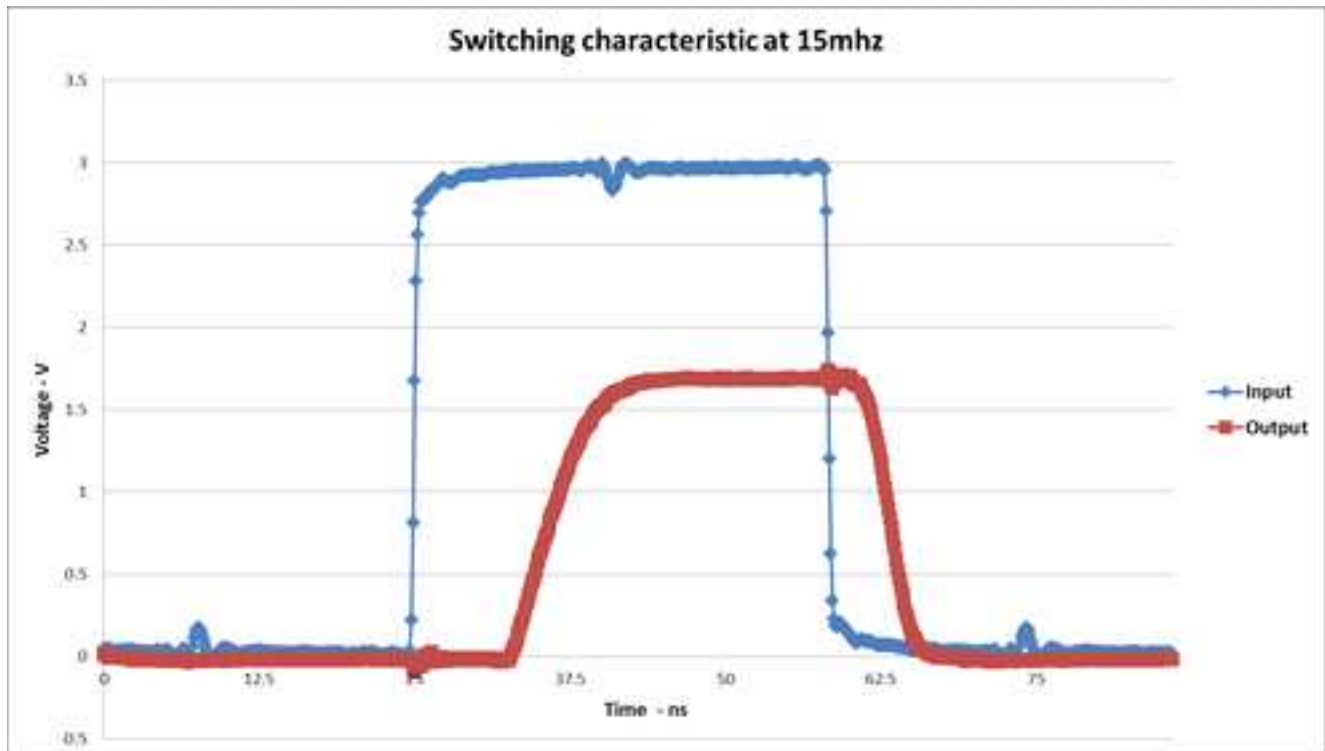**Figure 3. Excellent Signal Integrity (3.3V to 3.3V at 3.3V V$_{CC}$)**

Figure 4. Excellent Signal Integrity (3.3V to 1.8V at 1.8V V$_{CC}$)

Product Folder Links: *SN74LV1T32*
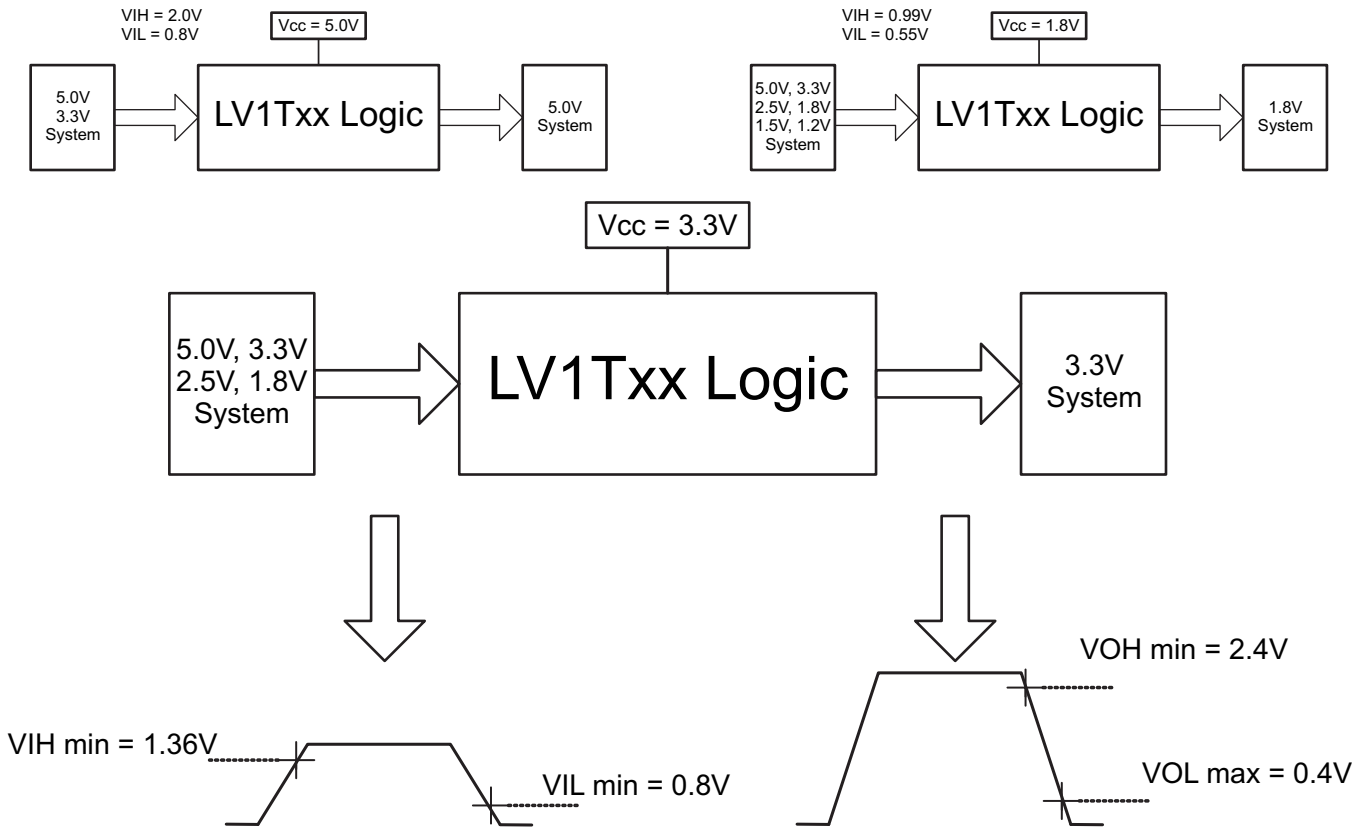
4.1 Typical Design Examples

Figure 5. Switching Thresholds for 1.8-V to 3.3-V Translation

4.2 Absolute Maximum Ratings[1]

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		−0.5	7.0	V
V_I	Input voltage range[2]		−0.5	7.0	V
V_O	Voltage range applied to any output in the high-impedance or power-off state[2]		−0.5	4.6	V
	Voltage range applied to any output in the high or low state[2]		−0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		−20	mA
I_{OK}	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$		±20	mA
I_O	Continuous output current			±25	mA
	Continuous current through V_{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance[3]	DBV package		206	°C/W
		DCK package		252	
		DRL package			
T_{stg}	Storage temperature range		−65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

4.3 Recommended Operating Conditions[(1)]

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V_{CC}	Supply voltage			1.6	5.5	V
V_I	Input voltage			0	5.5	V
V_O	Output voltage			0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.8 V			−3	mA
		V_{CC} = 2.5 V			−5	
		V_{CC} = 3.3 V			−7	
		V_{CC} = 5.0 V			−8	
I_{OL}	Low-level output current	V_{CC} = 1.8 V			3	mA
		V_{CC} = 2.5 V			5	
		V_{CC} = 3.3 V			7	
		V_{CC} = 5.0 V			8	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 1.8 V			20	ns/V
		V_{CC} = 3.3 V or 2.5 V			20	
		V_{CC} = 5.0 V			20	
T_A	Operating free-air temperature			−40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = −40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V_{IH}	High-level input voltage		1.65 V to 1.8 V	0.94			1.0		V
			2.0 V	0.99			1.03		
			2.25 V to 2.5 V	1.135			1.18		
			2.75 V	1.21			1.23		
			3 V to 3.3 V	1.35			1.37		
			3.6 V	1.47			1.48		
			4.5 V to 5.0 V	2.02			2.03		
			5.5 V	2.1			2.11		
V_{IL}	Low-level input voltage		1.65 V to 2.0 V			0.58		0.55	V
			2.25 V to 2.75 V			0.75		0.71	
			3 V to 3.6 V			0.8		0.65	
			4.5 V to 5.5 V			0.8		0.8	
V_{OH}		I_{OH} = −20 μA	1.65 V to 5.5 V	V_{CC} − 0.1			V_{CC} − 0.1		V
		I_{OH} = −2.0 mA	1.65 V	1.28			1.21		V
			1.8V	1.5			1.45		
		I_{OH} = −3 mA	2.3V	2.0			1.93		V
		I_{OH} = −3 mA	2.5V	2.25			2.15		V
		I_{OH} = −3.0 mA	3.0 V	2.78			2.7		V
		I_{OH} = −5.5 mA		2.6			2.49		
		I_{OH} = −5.5 mA	3.3 V	2.9			2.8		
		I_{OH} = −4 mA	4.5 V	4.2			4.1		V
		I_{OH} = −8 mA		4.1			3.95		
		I_{OH} = −8 mA	5.0 V	4.6			4.5		

Product Folder Links: *SN74LV1T32*

Electrical Characteristics (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = −40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V_{OL}		I_{OL} = 20 µA	1.65 V to 5.5 V			0.1		0.1	V
		I_{OL} = 2.0 mA	1.65 V			0.2		0.25	
		I_{OH} = 3 mA	2.3V			0.15		0.2	
		I_{OL} = 3 mA	3.0 V			0.1		0.15	
		I_{OL} = 5.5 mA				0.2		0.252	
		I_{OL} = 4 mA	4.5 V			0.15		0.2	
		I_{OL} = 8 mA				0.3		0.35	
I_I	A input	V_I = 0 V or V_{CC}	0V, 1.8V, 2.5V, 3.3V, 5.5V			0.1		±1	µA
I_{CC}		V_I = 0 V or V_{CC}, I_O = 0; open on loading	5.0 V			1		10	µA
			3.3 V			1		10	
			2.5 V			1		10	
			1.8V			1		10	
ΔI_{CC}		One input at 0.3V or 3.4V, Other inputs at 0 or V_{CC}, I_O = 0	5.5 V			1.35		1.5	mA
		One input at 0.3V or 1.1V Other inputs at 0 or V_{CC}, I_O = 0	1.8V			10		10	µA
C_i		V_I = V_{CC} or GND	3.3 V	2		10	2	10	pF
C_o		V_O = V_{CC} or GND	3.3 V			2.5		2.5	pF

4.5 Switching Characteristics

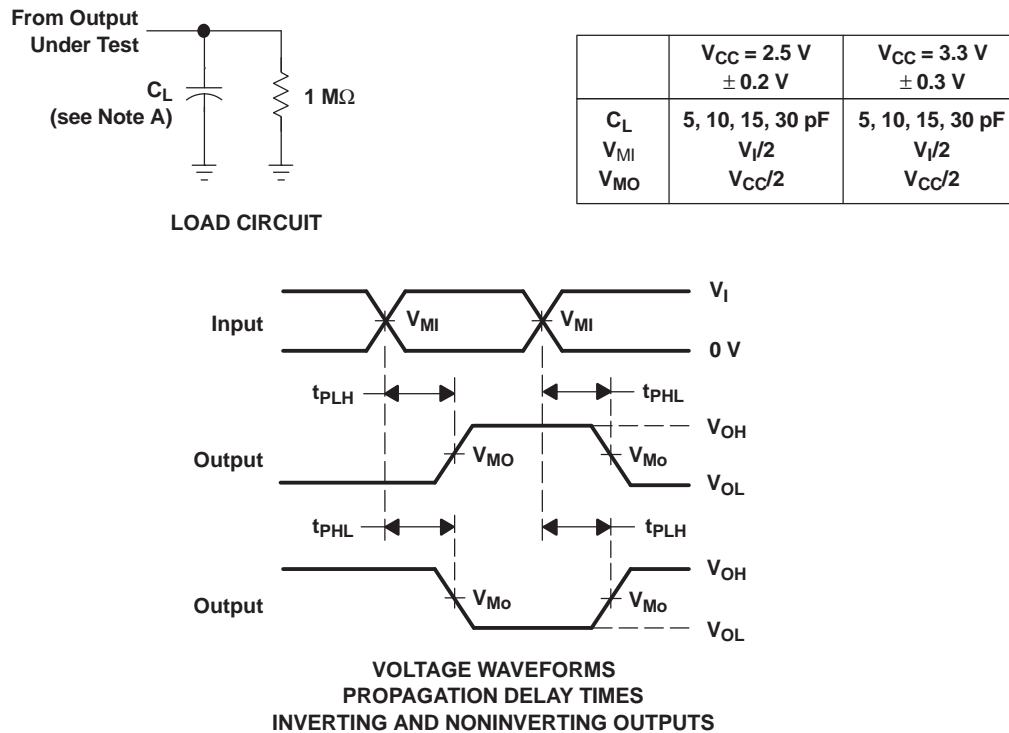over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	FREQUENCY (TYP)	V_{CC}	C_L	T_A = 25°C			T_A = −65°C to 125°C			UNIT
						MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Any In	Y	DC to 50 MHz	5.0V	15pF		4	5		4	5	ns
					30pF		5.5	7.0		5.5	7.0	
				3.3V	15pF		4.8	5		5	5.5	ns
					30pF		5	5.5		5.5	6.5	
			DC to 25 MHz	2.5V	15pF		6	6.5		7	7.5	ns
					30pF		6.5	7.5		7.5	8.5	
			DC to 15 MHz	1.8V	15pF		10.5	11		11	12	ns
					30pF		12	13		12	14	

4.6 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 1 MHz and 10 MHz	1.8 V ± 0.15 V	14	pF
			2.5 V ± 0.2 V	14	
			3.3 V ± 0.3 V	14	
			5.5 V ± 0.5 V	14	

5 Parameter Measurement Information

	V$_{CC}$ = 2.5 V ± 0.2 V	V$_{CC}$ = 3.3 V ± 0.3 V
C$_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V$_{MI}$	V$_I$/2	V$_I$/2
V$_{MO}$	V$_{CC}$/2	V$_{CC}$/2

LOAD CIRCUIT

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

NOTES: A. C$_L$ includes probe and jig capacitance.
         B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z$_O$ = 50 Ω, slew rate ≥ 1 V/ns.
         C. The outputs are measured one at a time, with one transition per measurement.
         D. t$_{PLH}$ and t$_{PHL}$ are the same as t$_{pd}$.

Figure 6. Load Circuit and Voltage Waveforms

5.1 More Product Selection

DEVICE	PACKAGE	DESCRIPTION
SN74LV1T00	DCK, DBV	2-Input Positive-NAND Gate
SN74LV1T02	DCK, DBV	2-Input Positive-NOR Gate
SN74LV1T08	DCK, DBV	Inverter Gate
SN74LV1T08	DCK, DBV	2-Input Positive-AND Gate
SN74LV1T17	DCK, DBV	Single Buffer Gate with 3-state Output
SN74LV1T14	DCK, DBV	Single Schmitt-Trigger Inverter Gate
SN74LV1T32	DCK, DBV	2-Input Positive-OR Gate
SN74LV1T50	DCK, DBV	Single Buffer Gate with 3-state Output
SN74LV1T86	DCK, DBV	Single 2-Input Exclusive-Or Gate
SN74LV1T125	DCK, DBV	Single Buffer Gate with 3-state Output
SN74LV1T126	DCK, DBV	Single Buffer Gate with 3-state Output
SN74LV4T125	RGY, PW	Quadruple Bus Buffer Gate With 3-State Outputs

Product Folder Links: *SN74LV1T32*

6 Device and Documentation Support

6.1 Trademarks

All trademarks are the property of their respective owners.

6.2 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.3 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

7 Mechanical, Packaging, and Orderable Information

The following packaging information and addendum reflect the most current data available for the designated devices. This data is subject to change without notice and revision of this document.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV1T32DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 125	(NEG3, NEGJ, NEGS)	Samples
SN74LV1T32DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	NEG3	Samples
SN74LV1T32DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(WG3, WGS)	Samples
SN74LV1T32DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		WG3	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
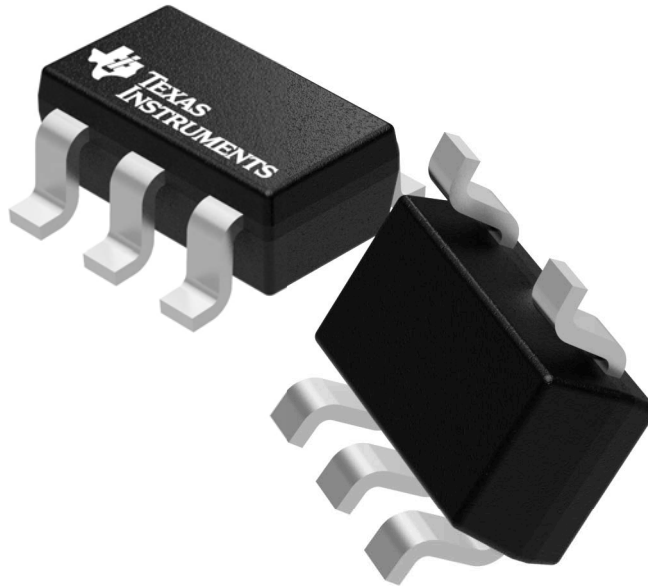
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DBV 5

Images above are just a representation of the package family, actual package may vary.
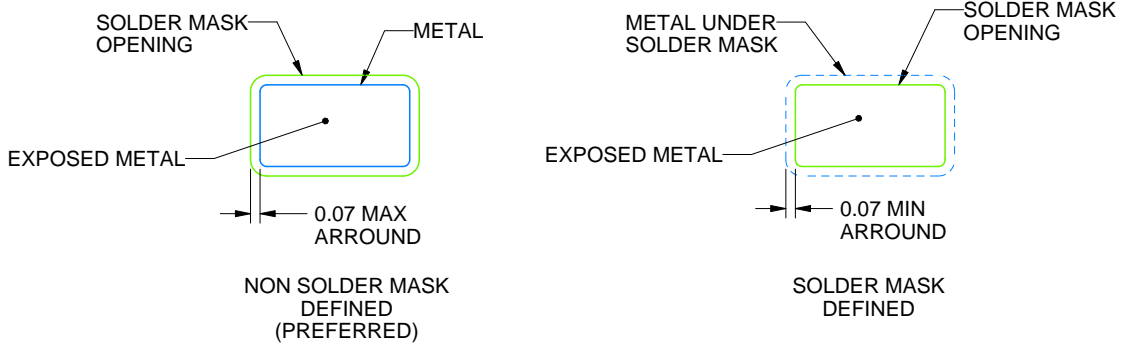Refer to the product data sheet for package details.

4073253/P

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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.

PKG
℄

5X (1.1)

1

5X (0.6)

5

2

SYMM
℄

(1.9)

2X (0.95)

3

4

(R0.05) TYP

(2.6)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.07 MAX
ARROUND

NON SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.07 MIN
ARROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4214839/C   04/2017

NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

PKG
$\mathbb{C}$

5X (1.1)

1

5X (0.6)

5

SYMM
$\mathbb{C}$

2

(1.9)

2X(0.95)

3

4

(R0.05) TYP

(2.6)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/C   04/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
7. Board assembly site may have different recommendations for stencil design.
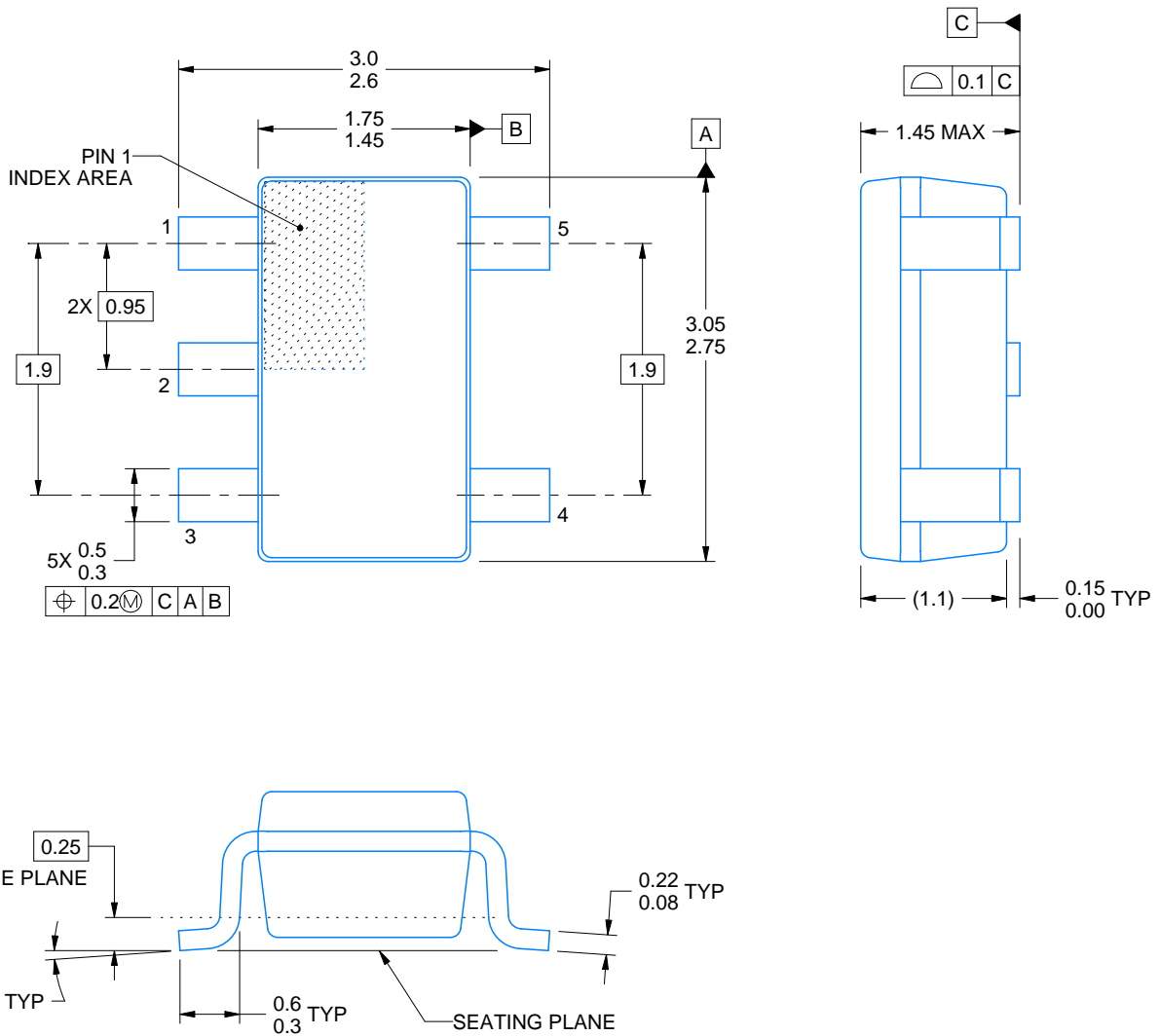
3.0
2.6

1.75
1.45

B

A

PIN 1
INDEX AREA

1

5

2X 0.95

1.9

2

3.05
2.75

1.9

5X 0.5
0.3

3

4

⊕ 0.2(M) C A B

C

0.1 C

1.45 MAX

(1.1)

0.15 TYP
0.00

0.25

GAGE PLANE

8°
0° TYP

0.6 TYP
0.3

SEATING PLANE

0.22 TYP
0.08

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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing
   per ASME Y14.5M.
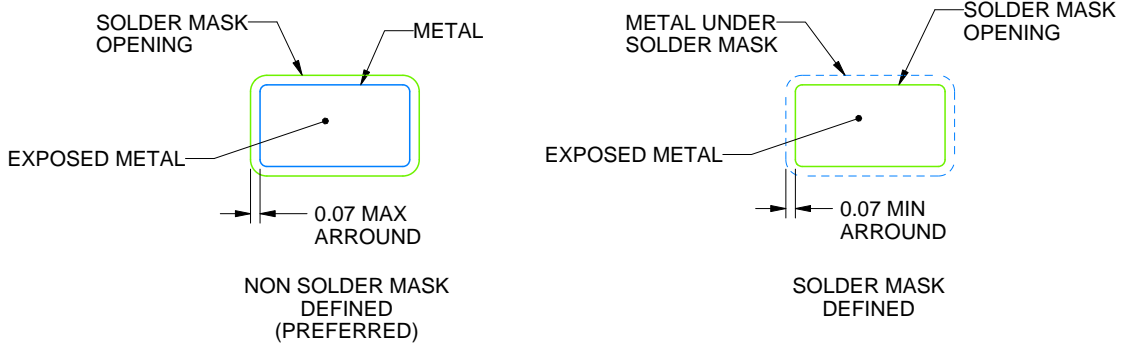2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.

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PKG
℄

5X (1.1)

1

5X (0.6)

5

SYMM
℄

2

(1.9)

2X (0.95)

3

4

(R0.05) TYP

(2.6)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.07 MAX
ARROUND

NON SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.07 MIN
ARROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4214839/C   04/2017

NOTES: (continued)

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5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

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SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/C   04/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
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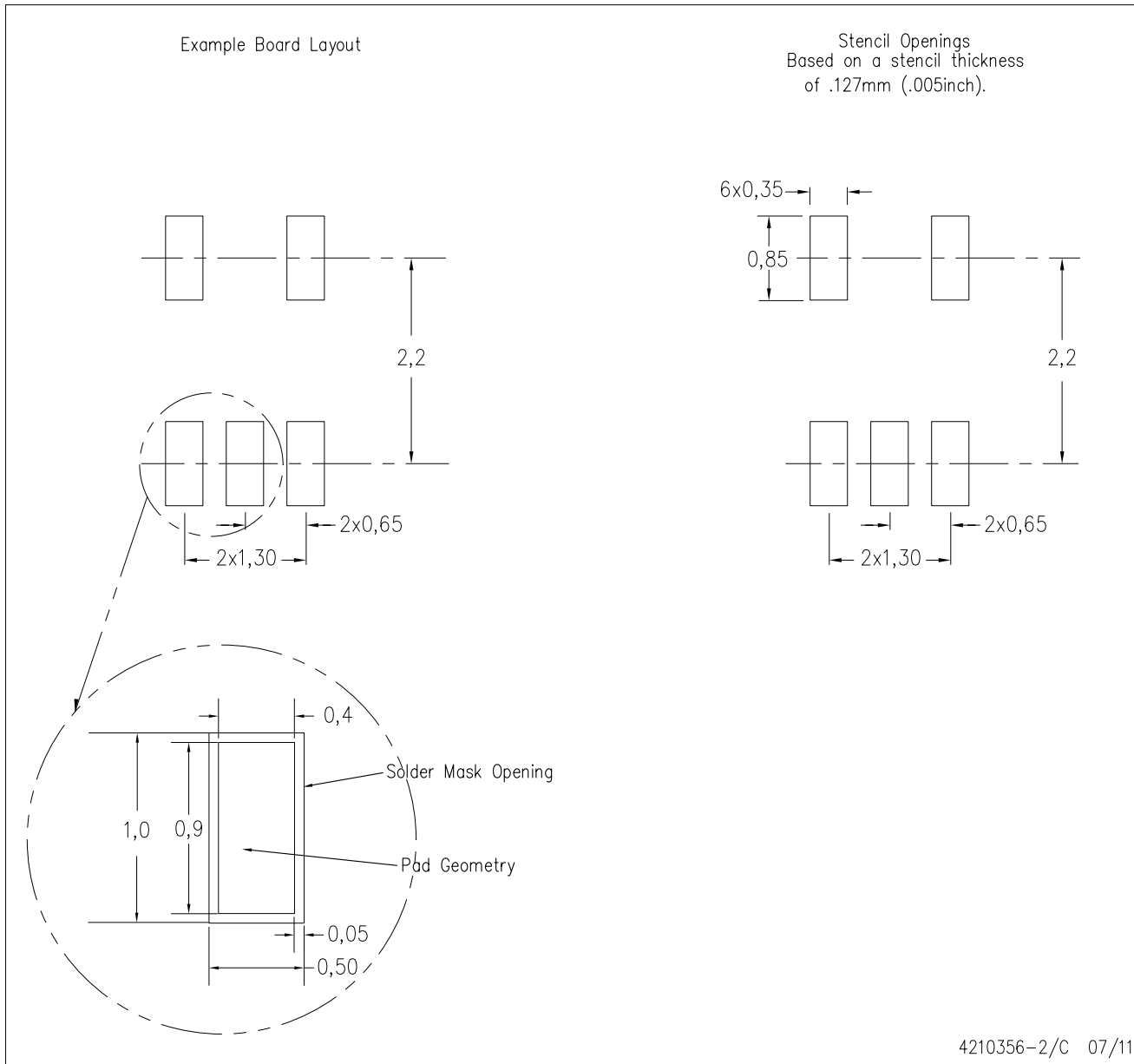
DCK (R−PDSO−G5)　　　　PLASTIC SMALL−OUTLINE PACKAGE

2,15 / 1,85

5　4

2,40 / 1,80

1,40 / 1,10

Pin 1
Index Area　1　　3

0,65

5X 0,30 / 0,15

⊕ 0,10 Ⓜ

1,30

0,22 / 0,08

Gauge Plane
Seating Plane

0,15　　0°−8°

0,46 / 0,26

1,10 / 0,80

⌒ 0,10

Seating Plane

0,10 / 0,00

4093553−3/G　01/2007

NOTES:　A.　All linear dimensions are in millimeters.
　　　　B.　This drawing is subject to change without notice.
　　　　C.　Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
　　　　D.　Falls within JEDEC MO−203 variation AA.

DCK (R−PDSO−G5)   PLASTIC SMALL OUTLINE

Example Board Layout

Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).

6x0,35

0,85

2,2

2,2

2x0,65

2x1,30

2x0,65

2x1,30

0,4

Solder Mask Opening

1,0   0,9

Pad Geometry

0,05

0,50

4210356−2/C 07/11

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
        D. Publication IPC−7351 is recommended for alternate designs.
        E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
            contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric
            metal load solder paste. Refer to IPC−7525 for other stencil recommendations.

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